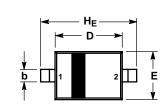


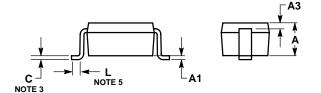
2

SOD-323 CASE 477-02

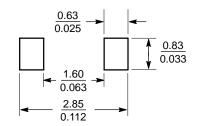
ISSUE H

STYLE 1 STYLE 2 SCALE 4:1





SOLDERING FOOTPRINT*



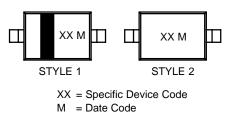
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DATE 13 MAR 2007

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- WITH SOLDER PLATING.
 A. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

GENERIC **MARKING DIAGRAM***



*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "•", may or may not be present.

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NEW STANDARD:		"CONTROLLED COPY" in red.
DESCRIPTION:	SOD-323	PAGE 1 OF 2

STYLE 2: NO POLARITY STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE





PAGE 2 OF 2

ISSUE	REVISION	DATE				
С	CHANGED OF OWNERSHIP FROM MOTOROLA TO ON SEMICONDUCTOR. ADDED SOD–323 IN USED ON SECTION. REQ. BY D. TRUHITTE.	30 APR 2002				
D	ADDED DIM L. ADDED NOTES 4 AND 5. REQ. BY M. DEWITT.	05 JAN 2004				
Е	CORRECTED TITLE. REQ. BY M. DEWITT.	12 JUL 2004				
F	ADDED NOM VALUES AND CHANGED DIMS TO INDUSTRY STANDARD. REQ. BY D. TRUHITTE.	31 JAN 2005				
G	CORRECTED ISSUE LETTER. REQ. BY J. LESLIE.	10 FEB 2005				
Н	CREATED CATHODE AND NON-CATHODE BAND OPTIONS. REQ. BY J. DAUGHERTY.	13 MAR 2007				

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